

### 25-Bit Configurable Registered Buffer for DDR2

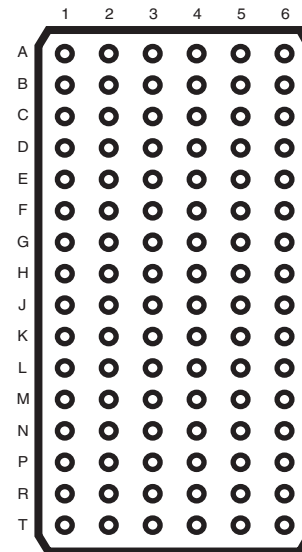
#### Recommended Application:

- DDR2 Memory Modules
- Provides complete DDR DIMM solution with ICS97U877
- Ideal for DDR2 400, 533, 667 and 800

#### Product Features:

- 25-bit 1:1 or 14-bit 1:2 configurable registered buffer
- Supports SSTL\_18 JEDEC specification on data inputs and outputs
- Supports LVCMOS switching levels on C0, C1 and RESET# inputs
- Low voltage operation  
V<sub>DD</sub> = 1.7V to 1.9V
- Available in 96 BGA package
- Drop-in replacement for ICSSSTUB32866
- Green packages available

#### Pin Configuration



**96 Ball BGA  
(Top View)**

#### Truth Table

Inputs						Outputs		
RST#	DCS#	CSR#	CK	CK#	Dn, DODT, DCKE	Qn	QCS#	QODT, QCKE
H	L	L	↑	↓	L	L	L	L
H	L	L	↑	↓	H	H	L	H
H	L	L	L or H	L or H	X	Q <sub>0</sub>	Q <sub>0</sub>	Q <sub>0</sub>
H	L	H	↑	↓	L	L	L	L
H	L	H	↑	↓	H	H	L	H
H	L	H	L or H	L or H	X	Q <sub>0</sub>	Q <sub>0</sub>	Q <sub>0</sub>
H	H	L	↑	↓	L	L	H	L
H	H	L	↑	↓	H	H	H	H
H	H	L	L or H	L or H	X	Q <sub>0</sub>	Q <sub>0</sub>	Q <sub>0</sub>
H	H	H	↑	↓	L	Q <sub>0</sub>	H	L
H	H	H	↑	↓	H	Q <sub>0</sub>	H	H
H	H	H	L or H	L or H	X	Q <sub>0</sub>	Q <sub>0</sub>	Q <sub>0</sub>
L	X or Floating	X or Floating	X or Floating	X or Floating	X or Floating	L	L	L

#### Ball Assignments

A	DCKE	NC	V <sub>REF</sub>	V <sub>DD</sub>	QCKE	NC
B	D2	D15	GND	GND	Q2	Q15
C	D3	D16	V <sub>DD</sub>	V <sub>DD</sub>	Q3	Q16
D	DODT	NC	GND	GND	QODT	NC
E	D5	D17	V <sub>DD</sub>	V <sub>DD</sub>	Q5	Q17
F	D6	D18	GND	GND	Q6	Q18
G	NC	RST#	V <sub>DD</sub>	V <sub>DD</sub>	C1	C0
H	CK	DCS#	GND	GND	QCS#	NC
J	CK#	CSR#	V <sub>DD</sub>	V <sub>DD</sub>	ZOH	ZOL
K	D8	D19	GND	GND	Q8	Q19
L	D9	D20	V <sub>DD</sub>	V <sub>DD</sub>	Q9	Q20
M	D10	D21	GND	GND	Q10	Q21
N	D11	D22	V <sub>DD</sub>	V <sub>DD</sub>	Q11	Q22
P	D12	D23	GND	GND	Q12	Q23
R	D13	D24	V <sub>DD</sub>	V <sub>DD</sub>	Q13	Q24
T	D14	D25	V <sub>REF</sub>	V <sub>DD</sub>	Q14	Q25

**1:1 Register (C0 = 0, C1 = 0)**

### Ball Assignments

A	DCKE	NC	V <sub>REF</sub>	V <sub>DD</sub>	QCKEA	QCKEB
B	D2	NC	GND	GND	Q2A	Q2B
C	D3	NC	V <sub>DD</sub>	V <sub>DD</sub>	Q3A	Q3B
D	DODT	NC	GND	GND	QODTA	QODTB
E	D5	NC	V <sub>DD</sub>	V <sub>DD</sub>	Q5A	Q5B
F	D6	NC	GND	GND	Q6A	Q6B
G	NC	RST#	V <sub>DD</sub>	V <sub>DD</sub>	C1	C0
H	CK	DCS#	GND	GND	QCSA#	QCSB#
J	CK#	CSR#	V <sub>DD</sub>	V <sub>DD</sub>	ZOH	ZOL
K	D8	NC	GND	GND	Q8A	Q8B
L	D9	NC	V <sub>DD</sub>	V <sub>DD</sub>	Q9A	Q9B
M	D10	NC	GND	GND	Q10A	Q10B
N	D11	NC	V <sub>DD</sub>	V <sub>DD</sub>	Q11A	Q11B
P	D12	NC	GND	GND	Q12A	Q12B
R	D13	NC	V <sub>DD</sub>	V <sub>DD</sub>	Q13A	Q13B
T	D14	NC	V <sub>REF</sub>	V <sub>DD</sub>	Q14A	Q14B
	1	2	3	4	5	6

1:2 Register A (C0 = 0, C1 = 1)

### Ball Assignments

A	D1	NC	V <sub>REF</sub>	V <sub>DD</sub>	Q1A	Q1B
B	D2	NC	GND	GND	Q2A	Q2B
C	D3	NC	V <sub>DD</sub>	V <sub>DD</sub>	Q3A	Q3B
D	D4	NC	GND	GND	Q4A	Q4B
E	D5	NC	V <sub>DD</sub>	V <sub>DD</sub>	Q5A	Q5B
F	D6	NC	GND	GND	Q6A	Q6B
G	NC	RST#	V <sub>DD</sub>	V <sub>DD</sub>	C1	C0
H	CK	DCS#	GND	GND	QCSA#	QCSB#
J	CK#	CSR#	V <sub>DD</sub>	V <sub>DD</sub>	ZOH	ZOL
K	D8	NC	GND	GND	Q8A	Q8B
L	D9	NC	V <sub>DD</sub>	V <sub>DD</sub>	Q9A	Q9B
M	D10	NC	GND	GND	Q10A	Q10B
N	DODT	NC	V <sub>DD</sub>	V <sub>DD</sub>	QODTA	QODTB
P	D12	NC	GND	GND	Q12A	Q12B
R	D13	NC	V <sub>DD</sub>	V <sub>DD</sub>	Q13A	Q13B
T	DCKE	NC	V <sub>REF</sub>	V <sub>DD</sub>	QCKEA	QCKEB
	1	2	3	4	5	6

1:2 Register B (C0 = 1, C1 = 1)

## General Description

This 25-bit 1:1 or 14-bit 1:2 configurable registered buffer is designed for 1.7-V to 1.9-V VDD operation.

All clock and data inputs are compatible with the JEDEC standard for SSTL\_18. The control inputs are LVCMOS. All outputs are 1.8-V CMOS drivers that have been optimized to drive the DDR-II DIMM load. **ICSSSTUB32864A** operates from a differential clock (CK and CK#). Data are registered at the crossing of CK going high, and CK# going low.

The C0 input controls the pinout configuration of the 1:2 pinout from A configuration (when low) to B configuration (when high). The C1 input controls the pinout configuration from 25-bit 1:1 (when low) to 14-bit 1:2 (when high).

The device supports low-power standby operation. When the reset input (RST#) is low, the differential input receivers are disabled, and undriven (floating) data, clock and reference voltage (VREF) inputs are allowed. In addition, when RST# is low all registers are reset, and all outputs are forced low. The LVCMOS RST# and Cn inputs must always be held at a valid logic high or low level. To ensure defined outputs from the register before a stable clock has been supplied, RST# must be held in the low state during power up.

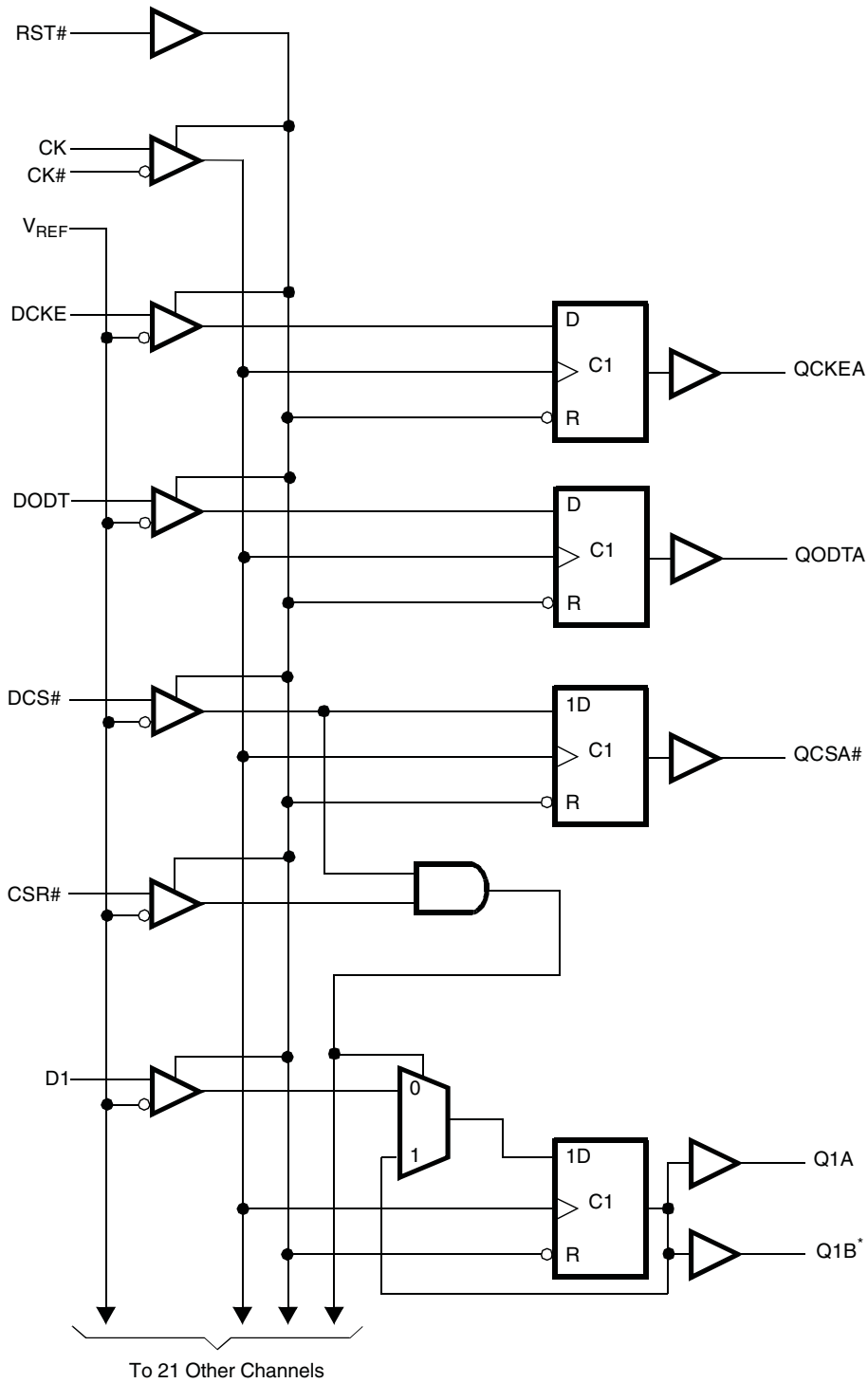
In the DDR-II RDIMM application, RST# is specified to be completely asynchronous with respect to CK and CK#. Therefore, no timing relationship can be guaranteed between the two. When entering reset, the register will be cleared and the outputs will be driven low quickly, relative to the time to disable the differential input receivers. However, when coming out of reset, the register will become active quickly, relative to the time to enable the differential input receivers. As long as the data inputs are low, and the clock is stable during the time from the low-to-high transition of RST# until the input receivers are fully enabled, the design of the **ICSSSTUB32864A** must ensure that the outputs will remain low, thus ensuring no glitches on the output.

The device monitors both DCS# and CSR# inputs and will gate the Qn outputs from changing states when both DCS# and CSR# inputs are high. If either DCS# or CSR# input is low, the Qn outputs will function normally. The RST input has priority over the DCS# and CSR# control and will force the outputs low. If the DCS#-control functionality is not desired, then the CSR# input can be hardwired to ground, in which case, the setup-time requirement for DCS# would be the same as for the other D data inputs. Package options include 96-ball LFBGA (MO-205CC).

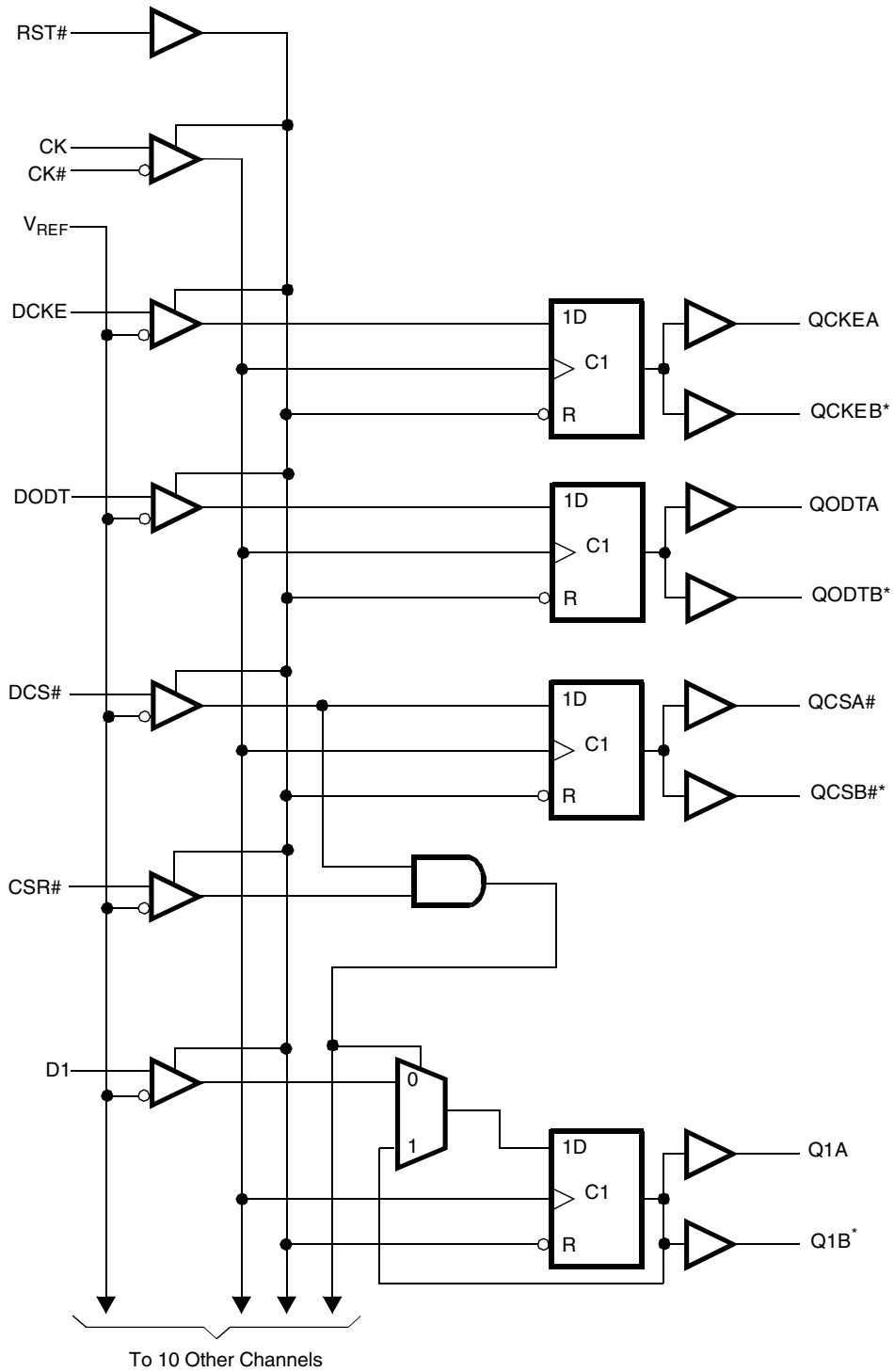
## Ball Assignment

Terminal Name	Description	Electrical Characteristics
GND	Ground	Ground input
V <sub>DD</sub>	Power supply voltage	1.8V nominal
V <sub>REF</sub>	Input reference voltage	0.9V nominal
Z <sub>OH</sub>	Reserved for future use	Input
Z <sub>OL</sub>	Reserved for future use	Input
CK	Positive master clock input	Differential input
CK#	Negative master clock input	Differential input
C0, C1	Configuration control inputs	LVC MOS inputs
RST#	Asynchronous reset input - resets registers and disables V <sub>REF</sub> data and clock differential-input receivers	LVC MOS input
CSR#, DCS#	Chip select inputs - disables D1 - D24 outputs switching when both inputs are high	SSTL <sub>18</sub> input
D1 - D25	Data input - clock in on the crossing of the rising edge of CK and the falling edge of CK#	SSTL <sub>18</sub> input
DODT	The outputs of this register bit will not be suspended by the DCS# and CSR# control	SSTL <sub>18</sub> input
DCKE	The outputs of this register bit will now be suspended by the DCS# and CSR# control	SSTL <sub>18</sub> input
Q1 - Q25	Data outputs that are suspended by the DCS# and CSR# control	1.8V CMOS
QCS#	Data output that will not be suspended by the DCS# and CSR# control	1.8V CMOS
QODT	Data output that will not be suspended by the DCS# and CSR# control	1.8V CMOS
QCKE	Data output that will not be suspended by the DCS# and CSR# control	1.8V CMOS

Block Diagram for 1:1 mode (positive logic)



Block Diagram for 1:2 mode (positive logic)



\*Note: Disabled in 1:1 configuration

## Absolute Maximum Ratings

Storage Temperature	-65°C to +150°C
Supply Voltage	-0.5V to 2.5V
Input Voltage <sup>1,2</sup>	-0.5V to +2.5V
Output Voltage <sup>1,2</sup>	-0.5V to VDD + 0.5V
Input Clamp Current	±50 mA
Output Clamp Current	±50mA
Continuous Output Current	±50mA
VDD or GND Current/Pin	±100mA
Package Thermal Impedance <sup>3</sup>	36°C

### Notes:

1. The input and output negative voltage ratings may be excluded if the input and output clamp ratings are observed.
2. This value is limited to 2.5V maximum.
3. The package thermal impedance is calculated in accordance with JESD 51.

Stresses above those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These ratings are stress specifications only and functional operation of the device at these or any other conditions above those listed in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

## Recommended Operating Conditions

PARAMETER	DESCRIPTION		MIN	TYP	MAX	UNITS	
V <sub>DD</sub>	I/O Supply Voltage		1.7	1.8	1.9	V	
V <sub>REF</sub>	Reference Voltage		0.49 x V <sub>DD</sub>	0.5 x V <sub>DD</sub>	0.51 x V <sub>DD</sub>		
V <sub>TT</sub>	Termination Voltage		V <sub>REF</sub> - 0.04	V <sub>REF</sub>	V <sub>REF</sub> + 0.04		
V <sub>I</sub>	Input Voltage		0		V <sub>DD</sub>		
V <sub>IH(DC)</sub>	DC Input High Voltage	Data Inputs	V <sub>REF</sub> + 0.125				
V <sub>IH(AC)</sub>	AC Input High Voltage		V <sub>REF</sub> + 0.250				
V <sub>IL(DC)</sub>	DC Input Low Voltage				V <sub>REF</sub> - 0.125		
V <sub>IL(AC)</sub>	AC Input Low Voltage				V <sub>REF</sub> - 0.250		
V <sub>IH</sub>	Input High Voltage Level	RESET#, C0, C1	0.65 x V <sub>DD</sub>				
V <sub>IL</sub>	Input Low Voltage Level				0.35 x V <sub>DD</sub>		
V <sub>ICR</sub>	Common mode Input Range	CLK, CLK#	0.675		1.125		
V <sub>ID</sub>	Differential Input Voltage		0.600				
I <sub>OH</sub>	High-Level Output Current				-8		mA
I <sub>OL</sub>	Low-Level Output Current				8		
T <sub>A</sub>	Operating Free-Air Temperature		0		70	°C	

<sup>1</sup>Guaranteed by design, not 100% tested in production.

Note: Reset# and Cn inputs must be held at valid logic levels (not floating) to ensure proper device operation. The differential inputs must not be floating unless Reset# is low.

## Electrical Characteristics - DC

$T_A = 0 - 70^\circ\text{C}$ ;  $V_{DD} = 1.8 \pm 0.1\text{V}$  (unless otherwise stated)

SYMBOL	PARAMETERS	CONDITIONS	$V_{DD}$	MIN	TYP	MAX	UNITS
$V_{IK}$		$I_I = -18\text{mA}$				-1.2	V
$V_{OH}$		$I_{OH} = -6\text{mA}$	1.7V	1.2			
$V_{OL}$		$I_{OL} = 6\text{mA}$	1.7V			0.5	
$I_I$	All Inputs	$V_I = V_{DD}$ or GND	1.9V	-5		5	$\mu\text{A}$
$I_{DD}$	Standby (Static)	RESET# = GND	1.9V			100	$\mu\text{A}$
	Operating (Static)	$V_I = V_{IH(AC)}$ or $V_{IL(AC)}$ , RESET# = $V_{DD}$			40		
$I_{DDD}$	Dynamic operating (clock only)	RESET# = $V_{DD}$ , $V_I = V_{IH(AC)}$ or $V_{IL(AC)}$ , CLK and CLK# switching 50% duty cycle.	1.8V		39		$\mu/\text{clock}$ MHz
	Dynamic Operating (per each data input) 1:1 mode	RESET# = $V_{DD}$ , $V_I = V_{IH(AC)}$ or $V_{IL(AC)}$ , CLK and CLK# switching 50% duty cycle. One data			19		$\mu\text{A}/\text{clock}$ MHz/data
	Dynamic Operating (per each data input) 1:2 mode	input switching at half clock frequency, 50% duty cycle			35		
$C_i$	Data Inputs	$V_I = V_{REF} \pm 350\text{mV}$		2.5		3.5	pF
	CLK and CLK#	$V_{ICR} = 1.25\text{V}$ , $V_{I(PP)} = 360\text{mV}$		2		3	
	RESET#	$V_I = V_{DD}$ or GND			2.5		

Notes:

1 - Guaranteed by design, not 100% tested in production.

## Timing Requirements

(over recommended operating free-air temperature range, unless otherwise noted)

SYMBOL	PARAMETERS		MIN	MAX	UNITS
$f_{\text{clock}}$	Clock frequency			410	MHz
$t_w$	Pulse duration, CK, CK High or Low		1		ns
$t_{\text{ACT}}$	Differential inputs active time (See notes 1 and 2)			10	ns
$t_{\text{INACT}}$	Differential inputs inactive time (See notes 1 and 3)			15	ns
	Setup time	DCS before CK, CK↓, CSR high; CSR before CK, CK↓, DCS high	0.6		ns
$t_{\text{SU}}$	Setup time	DCS before CK, CK↓, CSR Low	0.5		ns
		DODT, DCKE and data before CK, CK↓	0.5		ns
$t_h$	Hold time	DCS, DODT, DCKE and data after CK, CK↓	0.4		ns
		PAR_IN after CK, CK↓	0.4		ns

- Notes:**
- 1 - Guaranteed by design, not 100% tested in production.
  - 2 - For data signal input slew rate of 1V/ns.
  - 3 - For data signal input slew rate of 0.5V/ns and < 1V/ns.
  - 4 - CLK/CLK# signal input slew rate of 1V/ns.

## Switching Characteristics

(over recommended operating free-air temperature range, unless otherwise noted)

SYMBOL	From (Input)	To (Output)	$V_{\text{DD}} = 1.8\text{V} \pm 0.1\text{V}$			UNITS
			MIN	TYP	MAX	
$f_{\text{max}}$			410			MHz
$t_{\text{PDM}}^1$	CLK, CLK#	Q	1.1		1.5	ns
$t_{\text{PDMSS}}^2$	CLK, CLK#	Q			1.6	
$t_{\text{phl}}$	RESET#	Q			3	ns

- Notes: 1. Includes 350ps test-load transmission-line delay  
 2. Guaranteed by design, not 100% tested in production.

## Output Buffer Characteristics

Output edge rates over recommended operating free-air temperature range (See figure 7)

PARAMETER	$V_{\text{DD}} = 1.8\text{V} \pm 0.1\text{V}$		UNIT
	MIN	MAX	
$dV/dt_r$	1	4	V/ns
$dV/dt_f$	1	4	V/ns
$dV/dt_{\Delta}^1$		1	V/ns

1. Difference between  $dV/dt_r$  (rising edge rate) and  $dV/dt_f$  (falling edge rate)



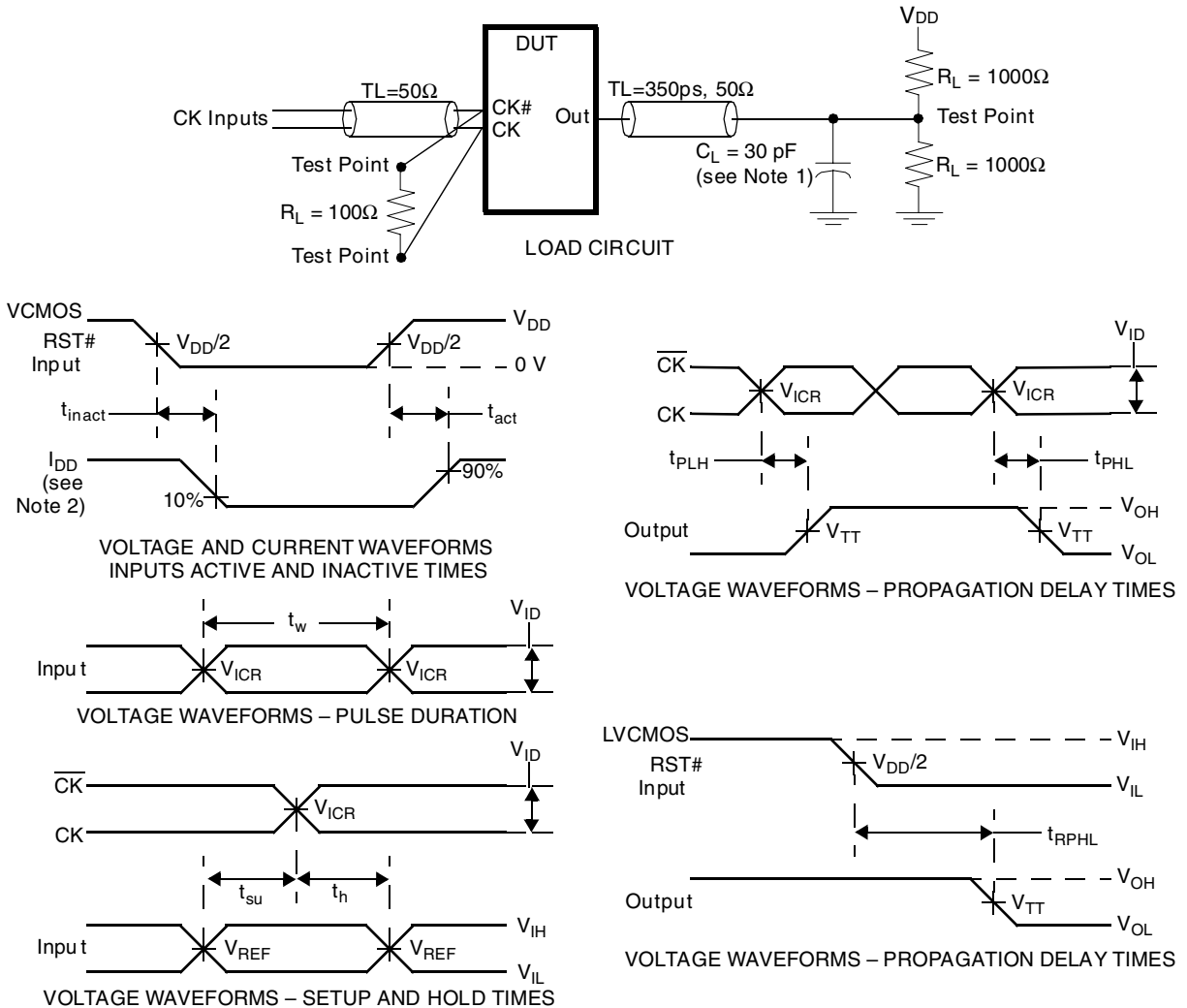


Figure 6— Parameter Measurement Information ( $V_{DD} = 1.8\text{ V} \pm 0.1\text{ V}$ )

- Notes:
1.  $C_L$  includes probe and jig capacitance.
  2.  $I_{DD}$  tested with clock and data inputs held at  $V_{DD}$  or GND, and  $I_o = 0\text{ mA}$ .
  3. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10\text{ MHz}$ ,  $Z_o = 50\Omega$ , input slew rate =  $1\text{ V/ns} \pm 20\%$  (unless otherwise specified).
  4. The outputs are measured one at a time with one transition per measurement.
  5.  $V_{REF} = V_{DD}/2$
  6.  $V_{IH} = V_{REF} + 250\text{ mV}$  (ac voltage levels) for differential inputs.  $V_{IH} = V_{DD}$  for LVCMOS input.
  7.  $V_{IL} = V_{REF} - 250\text{ mV}$  (ac voltage levels) for differential inputs.  $V_{IL} = \text{GND}$  for LVCMOS input.
  8.  $V_{ID} = 600\text{ mV}$
  9.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{PDM}$ .

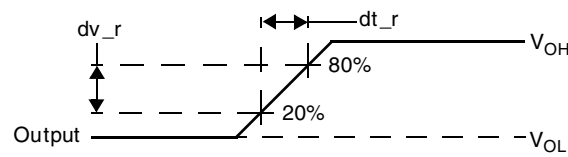
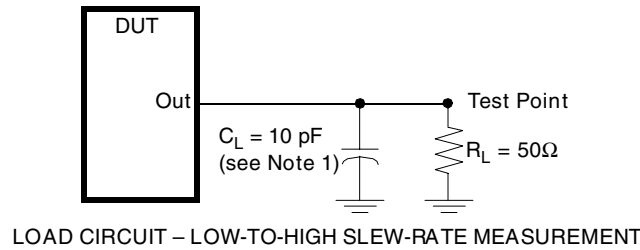
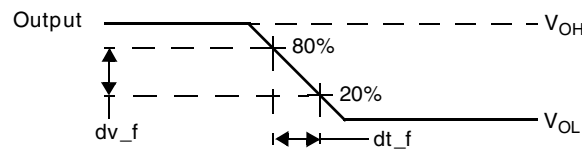
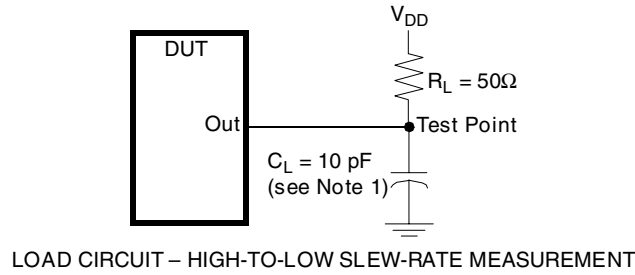
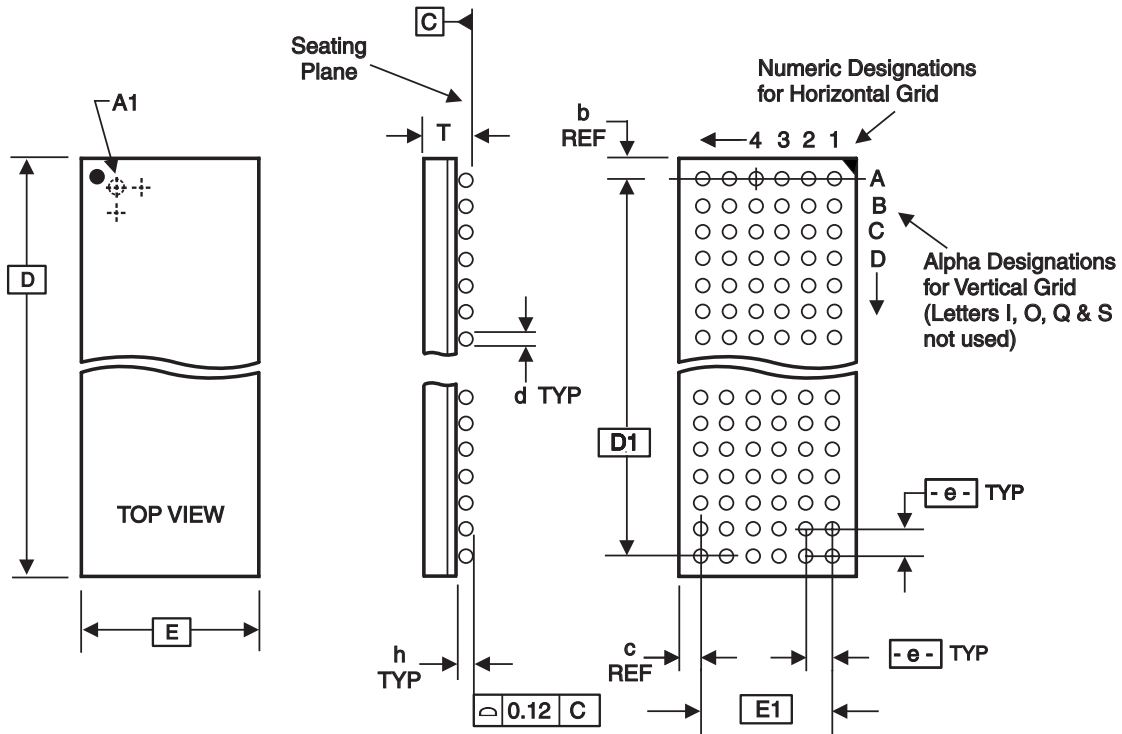


Figure 7 — Output Slew-Rate Measurement Information ( $V_{DD} = 1.8V \pm 0.1V$ )

Notes: 1.  $C_L$  includes probe and jig capacitance.

2. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10MHz$ ,  $Z_O = 50\Omega$ , input slew rate =  $1 V/ns \pm 20\%$  (unless otherwise specified).



ALL DIMENSIONS IN MILLIMETERS

D	E	T	e	BALL GRID		Max. TOTAL	d	h	REF. DIMENSIONS	
				HORIZ	VERT				b	c
		Min/Max					Min/Max	Min/Max		
13.50 Bsc	5.50 Bsc	1.30/1.50	0.80 Bsc	6	16	96	0.40/0.50	0.25/0.41	0.75	0.75
11.50 Bsc	5.00 Bsc	/1.2	0.65 Bsc	6	16	96	0.38/0.48	0.27/0.37	0.875	0.875

Note: Ball grid total indicates maximum ball count for package. Lesser quantity may be used.

\* Source Ref.: JEDEC Publication 95, MO-205

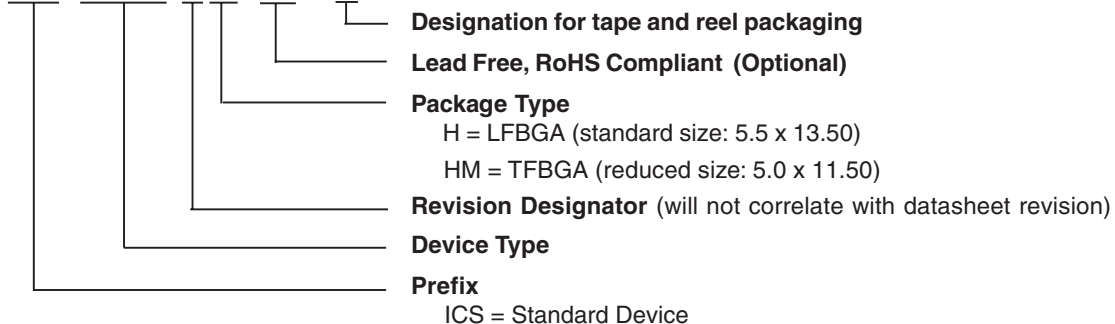
10-0055C

## Ordering Information

### ICSSSTUB32864Az(LF)T

Example:

ICS XXXX yz (LF) -T



**Revision History**

<b>Rev.</b>	<b>Issue Date</b>	<b>Description</b>	<b>Page #</b>
0.1	10/5/2005	Initial release	-

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